

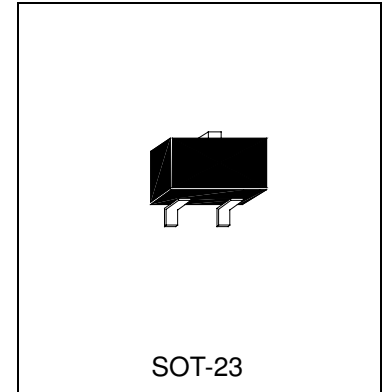


HMBT1815

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HMBT1815 is designed for use in driver stage of AF amplifier and general purpose amplification.



Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature..... -55 ~ +150 °C
 Junction Temperature..... 150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (T_A=25°C) 225 mW
- Maximum Voltages and Currents (T_A=25°C)
 V_{CBO} Collector to Base Voltage 60 V
 V_{CEO} Collector to Emitter Voltage 50 V
 V_{EBO} Emitter to Base Voltage 5 V
 I_C Collector Current 150 mA

Electrical Characteristics (T_A=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CBO}	60	-	-	V	I _C =100uA
BV _{CEO}	50	-	-	V	I _C =1mA
BV _{EBO}	5	-	-	V	I _E =10uA
I _{CBO}	-	-	100	nA	V _{CB} =60V
I _{EBO}	-	-	100	nA	V _{EB} =5V
*V _{CE(sat)}	-	-	250	mV	I _C =100mA, I _B =10mA
*V _{BE(sat)}	-	-	1	V	I _C =100mA, I _B =10mA
*h _{FE1}	120	-	700		V _{CE} =6V, I _C =2mA
*h _{FE2}	25	-	-		V _{CE} =6V, I _C =150mA
f _T	80	-	-	MHz	V _{CE} =10V, I _C =1mA, f=100MHz
Cob	-	-	3.5	pF	V _{CB} =10V, f=1MHz

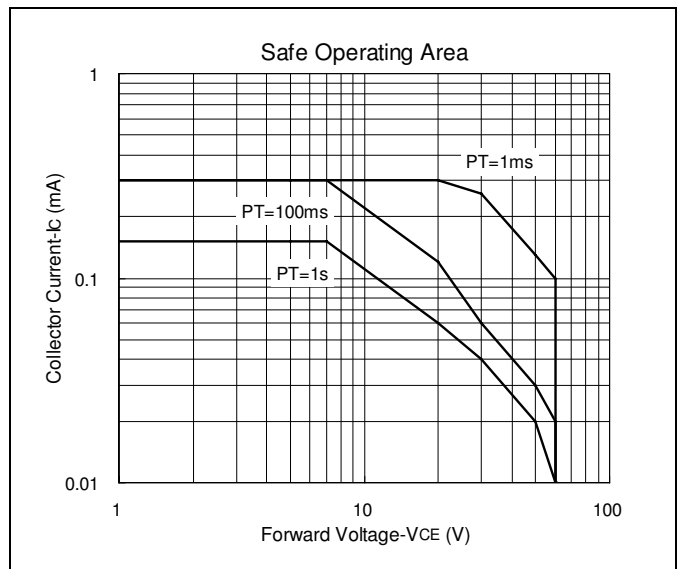
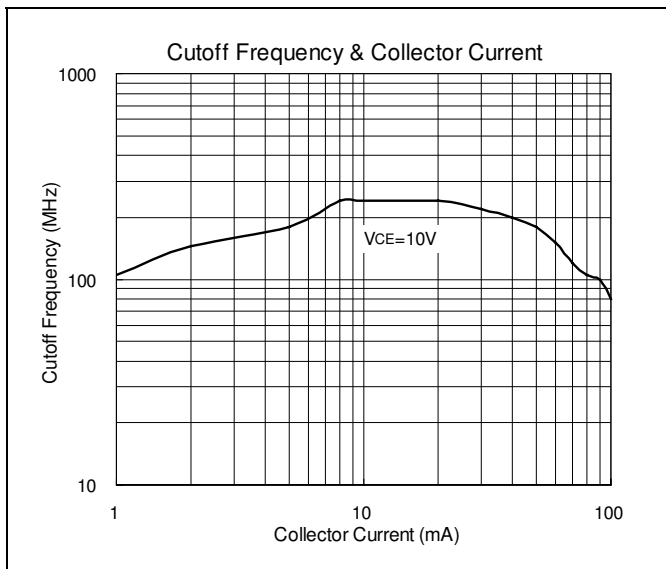
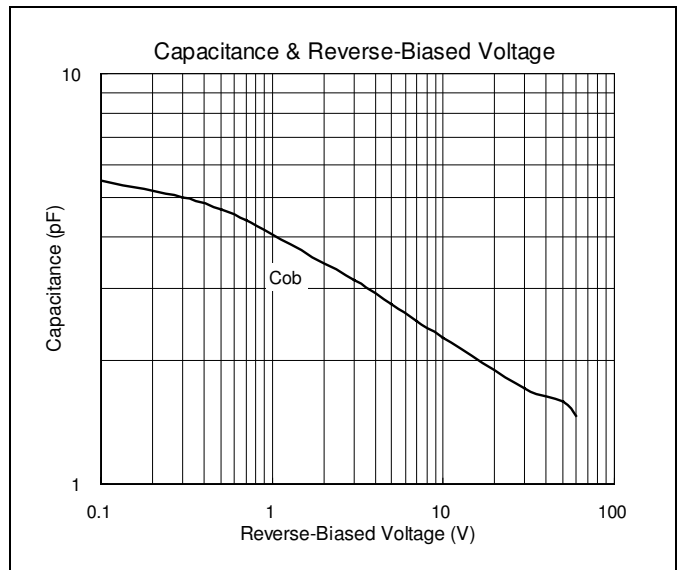
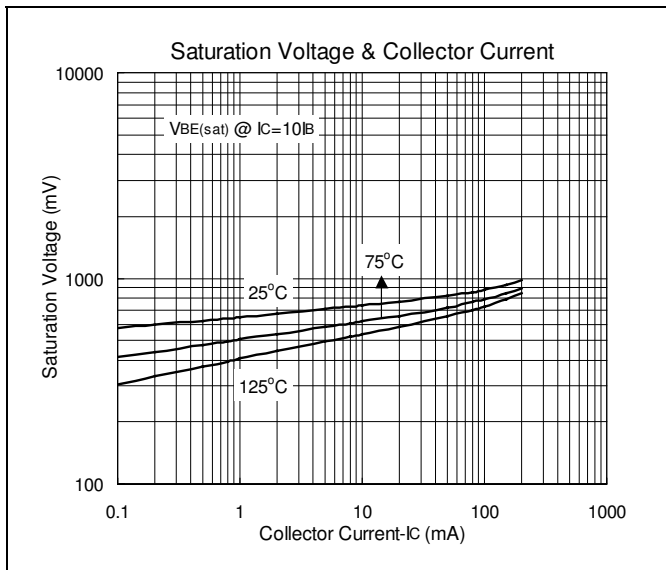
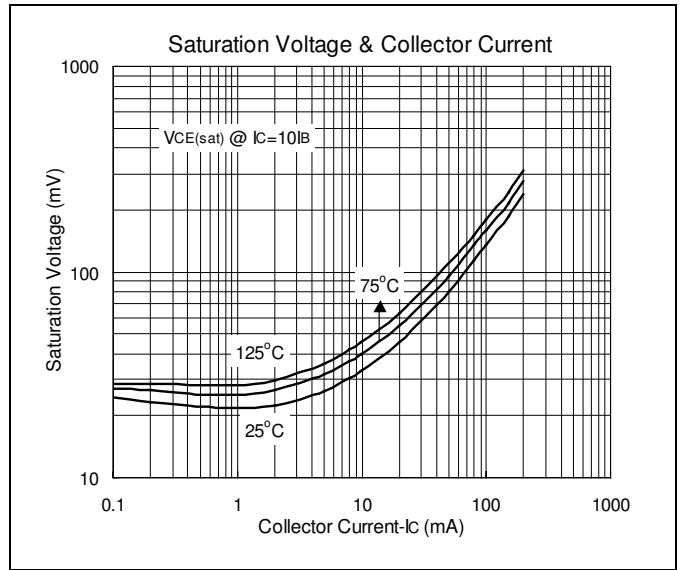
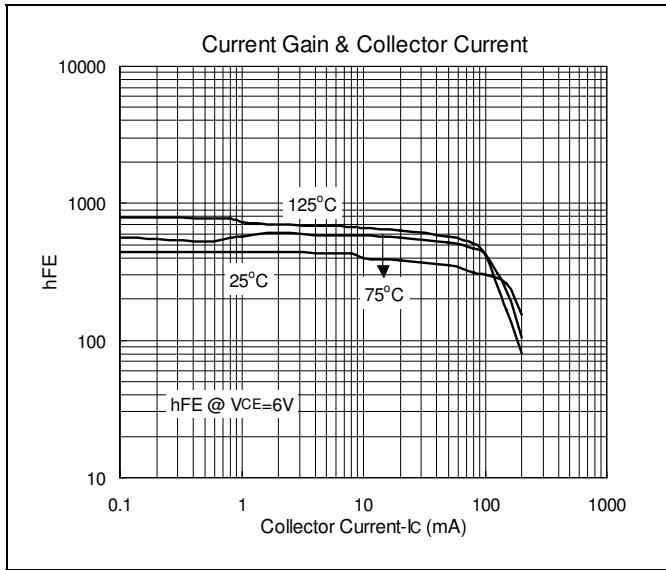
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

Classification Of hFE1

Rank	C4Y	C4G	C4B
Range	120-240	200-400	350-700



Characteristics Curve





SOT-23 Dimension

3-Lead SOT-23 Plastic
Surface Mounted Package
HSMC Package Code: N

Marking:

Note: Pb-free product can distinguish by the green label or the extra description on the right side of the label.

Pin Style: 1.Base 2.Emitter 3.Collector

Material:

- Lead solder plating: Sn60/Pb40 (Normal), Sn/3.0Ag/0.5Cu or Pure-Tin (Pb-free)
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

DIM	Min.	Max.
A	2.80	3.04
B	1.20	1.60
C	0.89	1.30
D	0.30	0.50
G	1.70	2.30
H	0.013	0.10
J	0.085	0.177
K	0.32	0.67
L	0.85	1.15
S	2.10	2.75
V	0.25	0.65

*: Typical, Unit: mm

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Head Office And Factory:

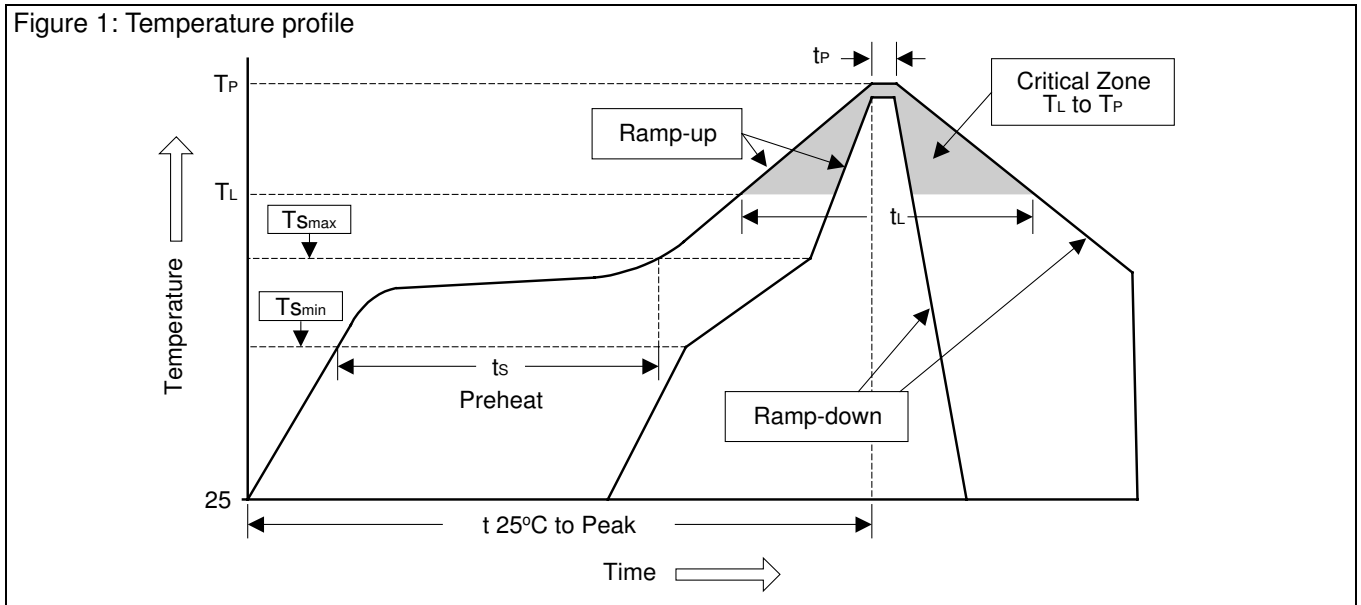
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Soldering Methods for HSMC's Products

1. Storage environment: Temperature=10°C~35°C Humidity=65%±15%
2. Reflow soldering of surface-mount devices

Figure 1: Temperature profile



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	<3°C/sec	<3°C/sec
Preheat		
- Temperature Min (T_{smin})	100°C	150°C
- Temperature Max (T_{smax})	150°C	200°C
- Time (min to max) (t_s)	60~120 sec	60~180 sec
T_{smax} to T_L		
- Ramp-up Rate	<3°C/sec	<3°C/sec
Time maintained above:		
- Temperature (T_L)	183°C	217°C
- Time (t_L)	60~150 sec	60~150 sec
Peak Temperature (T_P)	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature (t_P)	10~30 sec	20~40 sec
Ramp-down Rate	<6°C/sec	<6°C/sec
Time 25°C to Peak Temperature	<6 minutes	<8 minutes

3. Flow (wave) soldering (solder dipping)

Products	Peak temperature	Dipping time
Pb devices.	245°C ±5°C	5sec ±1sec
Pb-Free devices.	260°C +0/-5°C	5sec ±1sec